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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of Applicants:

Bietsch, et al.

Serial No.: 10/081,860

Filed: February 22, 2002

For: *SELECTIVE ETCHING OF SUBSTRATES WITH CONTROL OF THE ETCH PROFILE*

Date: January 17, 2005

Group Art Unit: 1751

Examiner: Lynette T Umez Eronini

Docket No.: CH920010003US1

Assistant Commissioner for Patents
Post Office Box 1450
Alexandria, VA 22313-1450

IN THE CLAIMS:

Cancel Claims 2 - 5 and 22 - 45 as drawn to a non-elected invention. Add Claims 46 and 47 to the invention under examination as these claims are sub-species of the claims upon which they depend.

In response to the Official Action dated January 6, 2005, please amend the above-identified application as set forth in the Appendix attached hereto.

REMARKS

Applicants acknowledge the requirement for restriction set forth in the Official Action.

Applicants confirm election of Claims 1 - 21 drawn to an etching composition. It is submitted that the claims as amended in the instant response will place the claims in condition for allowance so that process claims 22 - 45 drawn to the method of selectively patterning a substrate could be easily amended and also placed in condition for allowance. Applicants reserve the right to file a divisional application on the cancelled method claims.

The misspelling found in Claim 17 has been corrected.